## AS1751, AS1752, AS1753 <br> High-Speed, Low-Voltage, Single-Supply, $0.9 \Omega$, Quad SPST Analog Switches

## 1 General Description

The AS1751/AS1752/AS1753 are high-speed, low-voltage, quad single-pole/single-throw (SPST) analog switches.
Fast switching speeds, low ON-resistance, and low power consumption make these devices ideal for singlecell battery powered applications.

These highly-reliable devices operate from a single +1.6 to +3.6 V supply, and are differentiated by the type and number of switches:

- AS1751 - Four normally open (NO) switches
- AS1752 - Four normally closed (NC) switches
- AS1753 - Two NO switches and Two NC switches

The AS1753 supports break-before-make switching. With very low ON-resistance (Ron), Ron matching and Ron flatness, the devices can accurately switch signals for sample and hold circuits, digital filters, and op-amp gain switching networks.
The AS1751/AS1752/AS1753 digital logic input is 1.8 V CMOS-compatible when using a +3 V supply, and all devices can handle Rail-to-Rail signals.

The devices are available in a $3 \mathrm{~mm} \times 3 \mathrm{~mm} 16$-pin TQFN package and a 14-pin TSSOP package.

## 2 Key Features

- ON-Resistance:
- $0.9 \Omega$ (+3V supply)
- $2.5 \Omega$ (+1.8V supply)
- Ron Matching:
- $0.12 \Omega$ (+3V supply)
- $0.25 \Omega$ (+1.8V supply)
- Ron Flatness: $0.1 \Omega$ (+3V Supply)
- Supply Voltage Range: +1.6 to +3.6 V
- Switching Speed: ton $=22 \mathrm{~ns}$, toff $=14 \mathrm{~ns}$
- Current-Handling: 250 mA Continuous
- Break-Before-Make Switching (AS1753)
- Rail-to-Rail Signal Handling
- 1.8 V CMOS Logic Compatible (+3V Supply)
- Operating Temperature Range: -40 to $+85^{\circ} \mathrm{C}$
- Package Types:
- 16-pin TQFN (3mm x 3mm)
- 14-pin TSSOP


## 3 Applications

The devices are ideal for use in power routing systems, cordless and mobile phones, MP3 players, CD and DVD players, PDAs, handheld computers, digital cameras, hard drives, and any other application where high-speed signal switching is required.

Figure 1. 14-pin TSSOP Block Diagrams


| Device | Input | Switch State |  |
| :---: | :---: | :---: | :---: |
| AS1751 | Low | Off |  |
|  | High | On |  |
| AS1752 | Low | On |  |
|  | High | Off |  |
| AS1753 | Low | Switches 1, 3 = Off |  |
|  | High | Switches 1, 3 = On |  |
|  | Switches 2, 4 = On |  |  |

## 4 Pinout

## Pin Assignments

Figure 2. TQFN Pin Assignments (Top View)


Figure 3. TSSOP Pin Assignments (Top View)


## Pin Descriptions

Table 1. Pin Descriptions

| Pin Number | Pin Name | Description |
| :---: | :---: | :--- |
| (see Figure 2 <br> and Figure 3) | $\mathrm{COM} 1: \mathrm{COM} 4$ | Analog Switch 1, 2, 3, 4 Common |
|  | GND | Ground |
|  | IN1:IN4 | Analog Switch 1, 2, 3, 4 Logic Control Input |
|  | NC1:NC4 | Analog Switch 1, 2, 3, 4 Normally Closed Terminal |
|  | NO1:NO4 | Analog Switch 1, 2, 3, 4 Normally Open Terminal |

## 5 Absolute Maximum Ratings

Stresses beyond those listed in Table 2 may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in Electrical Characteristics on page 4 is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 2. Absolute Maximum Ratings

| Parameter |  | Min | Max | Units | Comments |
| :---: | :---: | :---: | :---: | :---: | :---: |
| V+, INx to GND |  | -0.3 | +5 | V |  |
| COMx, NOx, NCx to GND ${ }^{\dagger}$ |  | -0.3 | $\begin{gathered} \mathrm{V}+ \\ +0.3 \end{gathered}$ | V |  |
| COMx, NOx, NCx Continuous Current |  | -250 | +250 | mA |  |
| COMx, NOx, NCx Peak Current |  | -350 | +350 | mA | Pulsed at 1ms 10\% duty cycle |
| Continuous Power <br> Dissipation (TAMB $=+70^{\circ} \mathrm{C}$ ) | 16-pin TQFN |  | 727 | mW | Derate at $9.1 \mathrm{~W} /{ }^{\circ} \mathrm{C}$ above $+70^{\circ} \mathrm{C}$ |
|  | 14-pin TSSOP |  | 1349 |  | Derate at $16.9 \mathrm{~W} /{ }^{\circ} \mathrm{C}$ above $+70^{\circ} \mathrm{C}$ |
| Operating Temperature Range |  | -40 | +85 | ${ }^{\circ} \mathrm{C}$ |  |
| Electro-Static Discharge |  |  | 2500 | V | HBM Mil-Std883E 3015.7 methods |
| Latch Up Immunity |  |  | 250 | mA | Norm: JEDEC 17 |
| Junction Temperature |  |  | +150 | ${ }^{\circ} \mathrm{C}$ |  |
| Storage Temperature Range |  | -65 | +150 | ${ }^{\circ} \mathrm{C}$ |  |
| Package Body Temperature |  |  | +260 | ${ }^{\circ} \mathrm{C}$ | The reflow peak soldering temperature (body temperature) specified is in accordance with IPC/JEDEC J-STD-020C "Moisture/Reflow Sensitivity Classification for Non-Hermetic Solid State Surface Mount Devices" |

${ }^{\dagger}$ Signals on pins COM1, COM3, NO1, NO2, NC1, or NC2 that exceed $\mathrm{V}+$ or GND are clamped by internal diodes. For-ward-diode current should be limited to the maximum current rating.

## 6 Electrical Characteristics

Table 3. Power Supply Characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{V}+$ | Power Supply Range | TAmB $=$ Tmin to TMAX | 1.6 |  | 3.6 | V |
| $\mathrm{I}+$ | Positive Supply <br> Current | $\mathrm{V}+=3.6 \mathrm{~V}, \mathrm{VINx}=0$ or $\mathrm{V}+$, TAMB $=+25^{\circ} \mathrm{C}$ |  |  | 0.1 | $\mu \mathrm{~A}$ |

$V+=+2.7$ to $+3.6 \mathrm{~V}, \mathrm{VIH}=+1.4 \mathrm{~V}, \mathrm{VIL}=+0.5 \mathrm{~V}$, TAMB $=$ TMIN to $\operatorname{TMAX}$ (unless otherwise specified). Typ values @ $\mathrm{V}+=$ +3.0 V, TAMB $=+25^{\circ} \mathrm{C}$.
Table 4. +3V Supply Electrical Characteristics

| Symbol | Parameter | Conditions |  | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Analog Switch |  |  |  |  |  |  |  |
| Vcomx, VNOx, VNCx | Analog Signal Range |  |  | 0 |  | V+ | V |
| Ron | ON-Resistance | $\begin{aligned} \mathrm{V}+=2.7 \mathrm{~V}, \mathrm{Icomx} & =100 \mathrm{~mA} \\ \mathrm{~V} \text { NOx or } \mathrm{VNCx} & =1.5 \mathrm{~V} \end{aligned}$ | TAMB $=+25^{\circ} \mathrm{C}$ |  | 0.4 | 0.9 | $\Omega$ |
|  |  |  | TAMB $=$ TMIN to TMAX |  |  | 1 |  |
| $\triangle \mathrm{RoN}$ | ON-Resistance Match Between Channels ${ }^{1}$ | $\begin{aligned} \mathrm{V}+=2.7 \mathrm{~V}, \mathrm{Icomx} & =100 \mathrm{~mA} \\ \mathrm{~V} \text { NOx or } \mathrm{VNCx} & =1.5 \mathrm{~V} \end{aligned}$ | TAMB $=+25^{\circ} \mathrm{C}$ |  | 0.03 | 0.12 | $\Omega$ |
|  |  |  | TAMB $=$ TMIN to TMAX |  |  | 0.15 |  |
| RFLAT(ON) | ON-Resistance Flatness ${ }^{2}$ | $\mathrm{V}+=2.7 \mathrm{~V}, \mathrm{I} \text { сом } x=100 \mathrm{~mA}$ <br> $\mathrm{VNOx}^{\text {or }} \mathrm{VNCx}^{2}=1,1.5$, or 2 V | TAMB $=+25^{\circ} \mathrm{C}$ |  | 0.02 | 0.1 | $\Omega$ |
|  |  |  | TAMB $=$ TMIN to Tmax |  |  | 0.12 |  |
| INOX(OFF), INCx(OFF) | NOx or NCx Off-Leakage Current | $\begin{gathered} \mathrm{V}+=3.6 \mathrm{~V}, \\ \mathrm{Vcomx}=0.3 \text { or } 3.6 \mathrm{~V}, \\ \text { VNOx or } \mathrm{VNCx}=3.6 \text { or } 0.3 \mathrm{~V} \end{gathered}$ | TAMB $=+25^{\circ} \mathrm{C}$ | -2.5 |  | +2.5 | nA |
|  |  |  | TAMB $=$ TMIN to TMAX | -10 |  | +10 |  |
| ICOMx(OFF) | COM $x$ Off-Leakage Current | $\begin{gathered} \mathrm{V}+=3.6 \mathrm{~V} \\ \mathrm{Vcom} x=0.3 \text { or } 3.6 \mathrm{~V}, \end{gathered}$ <br> $\mathrm{VNOx}_{\mathrm{N}}$ or $\mathrm{VNCx}^{2}=3.6$ or 0.3 V | TAMB $=+25^{\circ} \mathrm{C}$ | -2.5 |  | +2.5 | nA |
|  |  |  | TAmb $=$ TMIN to Tmax | -10 |  | +10 |  |
| ICOMx(ON) | COMx On-Leakage Current | $\begin{gathered} \mathrm{V}+=3.6 \mathrm{~V}, \\ \mathrm{Vcomx}=0.3 \text { or } 3.6 \mathrm{~V}, \\ \text { VNOx or VNCx }=0.3 \text { or } 3.6 \mathrm{~V} \end{gathered}$ | TAMB $=+25^{\circ} \mathrm{C}$ | -2.5 |  | +2.5 | nA |
|  |  |  | TAmB $=$ Tmin to Tmax | -10 |  | +10 |  |

## Switch Dynamic Characteristics

| ton | Turn On Time ${ }^{3}$ | $\mathrm{V}_{\text {NOx }}$ or $\mathrm{VNCx}^{2}=1.5 \mathrm{~V}$, Rload $=50 \Omega$, Cload $=$ 35pF, Figures 13, 14 | TAMB $=+25^{\circ} \mathrm{C}$ |  | 16 | 22 | ns |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | TAMB $=$ TMIN to TMAX |  |  | 24 |  |
| toff | Turn Off Time ${ }^{3}$ | Vnox or $\mathrm{VNCx}^{2}=1.5 \mathrm{~V}$, Rload $=50 \Omega$, Cload $=$ 35pF, Figures 13, 14 | TAMB $=+25^{\circ} \mathrm{C}$ |  | 5 | 14 | ns |
|  |  |  | TAMB $=$ TMIN to TMAX |  |  | 15 |  |
| tBBM | Break-Before-Make ${ }^{3}$ | $\mathrm{V}_{\mathrm{NO}}$ or $\mathrm{VNCx}^{2}=1.5 \mathrm{~V}$, <br> Rload $=50 \Omega$, Cload $=$ 35pF, Figure 15 (AS1753) | TAMB $=+25^{\circ} \mathrm{C}$ |  | 11 |  | ns |
|  |  |  | TAmb $=$ Tmin to Tmax | 2 |  |  |  |
| Q | Charge Injection | Vgen $=\mathrm{V}+$, Rgen $=0, \mathrm{Cload}=1.0 n \mathrm{~F}$, Figure 16 |  |  | 2 |  | pC |
| Coff | NOx, NCx Off-Capacitance | $\mathrm{f}=1 \mathrm{MHz}$, Figure 17 |  |  | 45 |  | pF |
| Ccomx(OFF) | COM $x$ Off-Capacitance | $\mathrm{f}=1 \mathrm{MHz}$, Figure 17 |  |  | 49 |  | pF |
| Ccomx(ON) | COMx On-Capacitance | $\mathrm{f}=1 \mathrm{MHz}$, Figure 17 |  |  | 85 |  | pF |

Table 4. $+3 V$ Supply Electrical Characteristics (Continued)

| Symbol | Parameter | Conditions | Min | Tур | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Viso | Off-Isolation ${ }^{4}$ | $\mathrm{f}=10 \mathrm{MHz}$, RLoad $=50 \Omega, \mathrm{Cload}=5 \mathrm{pF}$, Figure 18 |  | -40 |  | dB |
|  |  | $\mathrm{f}=1 \mathrm{MHz}, \mathrm{Rload}=50 \Omega, \mathrm{ClOad}=5 \mathrm{pF}$, Figure 18 |  | -55 |  |  |
|  | Crosstalk ${ }^{5}$ | $\mathrm{f}=10 \mathrm{MHz}$, RLoad $=50 \Omega$, Cload $=5 \mathrm{pF}$, Figure 18 |  | -70 |  | dB |
|  |  | $\mathrm{f}=1 \mathrm{MHz}$, RLOAD $=50 \Omega$, Cload $=5 \mathrm{pF}$, Figure 18 |  | -80 |  |  |
| THD | Total Harmonic Distortion | $\mathrm{f}=20 \mathrm{~Hz}$ to $20 \mathrm{kHz}, \mathrm{Vcomx}=2 \mathrm{Vp}-\mathrm{p}, \mathrm{RLOAD}=32 \Omega$ |  | 0.033 |  | \% |
| Logic Input |  |  |  |  |  |  |
| VIH | Input Logic High |  | 1.4 |  |  | V |
| VIL | Input Logic Low |  |  |  | 0.5 | V |
| IIN | Input Leakage Current | V Inx $=0$ or $\mathrm{V}+$ | -1 | 0.0001 | +1 | $\mu \mathrm{A}$ |

$V+=+1.8 \mathrm{~V}, \mathrm{VIH}^{\prime}=+1.0 \mathrm{~V}, \mathrm{VIL}=0.4 \mathrm{~V}, \operatorname{TAMB}=\operatorname{TMIN}$ to $\operatorname{TMAX}$ (unless otherwise specified). Typ values @ TAMB $=+25^{\circ} \mathrm{C}$.
Table 5. +1.8V Supply Electrical Characteristics

| Symbol | Parameter | Conditions |  | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Analog Switch |  |  |  |  |  |  |  |
| Vcomx, Vnox, VnCx | Analog Signal Range |  |  | 0 |  | V+ | V |
| Ron | ON-Resistance | $\begin{gathered} \mathrm{V}+=1.8 \mathrm{~V}, \mathrm{ICOM} x=10 \mathrm{~mA}, \\ \mathrm{VNO} \text { or } \mathrm{VNCx}=0.9 \mathrm{~V} \end{gathered}$ | TAMB $=+25^{\circ} \mathrm{C}$ |  | 0.9 | 2.5 | $\Omega$ |
|  |  |  | TAMB $=$ TMIN to TMAX |  |  | 3 |  |
| $\Delta \mathrm{RoN}$ | ON-Resistance Match Between Channels ${ }^{1}$ | $\begin{gathered} \mathrm{V}+=1.8 \mathrm{~V}, \mathrm{ICOM} x=10 \mathrm{~mA}, \\ \mathrm{VNO} \text { or } \mathrm{VNCx}^{2}=0.9 \mathrm{~V} \end{gathered}$ | TAMB $=+25^{\circ} \mathrm{C}$ |  | 0.05 | 0.25 | $\Omega$ |
|  |  |  | TAmb $=$ Tmin to Tmax |  |  | 0.25 |  |
| Switch Dynamic Characteristics |  |  |  |  |  |  |  |
| ton | Turn On Time ${ }^{3}$ | $\mathrm{VNOx}^{\text {or }} \mathrm{VNCx}^{2}=1.0 \mathrm{~V}$, Rload $=50 \Omega$, Cload $=35 \mathrm{pF}$, Figures 13, 14 | TAMB $=+25^{\circ} \mathrm{C}$ |  | 22 | 30 | ns |
|  |  |  | TAmb $=$ TMIN to Tmax |  |  | 35 |  |
| toff | Turn Off Time ${ }^{3}$ | $\begin{gathered} \text { VNOx or } V_{N C x}=1.0 \mathrm{~V}, \\ \text { RLOAD }=50 \Omega, \text { CLOAD }=35 \mathrm{pF}, \\ \text { Figures } 13,14 \end{gathered}$ | TAMB $=+25^{\circ} \mathrm{C}$ |  | 12 | 20 | ns |
|  |  |  | TAmb $=$ Tmin to Tmax |  |  | 25 |  |
| Q | Charge Injection | Vgen $=\mathrm{V}+$, Rgen $=0, \mathrm{Cload}=1.0 n F$, Figure 16 |  |  | 1 |  | pC |
| Logic Input |  |  |  |  |  |  |  |
| VIH | Input Logic High |  |  | 1.0 |  |  | V |
| VIL | Input Logic Low |  |  |  |  | 0.4 | V |
| IIN | Input Leakage Current | VIN $x=0$ or |  | -1 | 0.0001 | +1 | $\mu \mathrm{A}$ |

1. $\Delta \operatorname{RON}=\operatorname{RON}(M A X)-\operatorname{Ron}(M I N)$.
2. Flatness is defined as the difference between the maximum and the minimum value of ON-resistance as measured over the specified analog signal ranges.
3. Guaranteed by design.
4. Off-Isolation $=20 \log 10(\mathrm{Vcom} x / \mathrm{VNOx}), \mathrm{Vcom} x=$ output, $\mathrm{VNO}=$ input to off switch.
5. Between two switches.

## 7 Typical Operating Characteristics

Figure 4. Frequency Response


Figure 6. Turn On/Turn Off Time vs. Temperature


Figure 8. Ron vs. VCom and Temperature; VDD $=2.7 \mathrm{~V}$


Figure 5. Total Harmonic Distortion vs. Frequency


Figure 7. Turn On/Off Time vs. Supply Voltage


Figure 9. Ron vs. VCom


Data Sheet - Typical Operating Characteristics

Figure 10. Charge Injection vs. Vсом


## 8 Detailed Description

The AS1751/AS1752/AS1753 are low ON-resistance, low-voltage, quad analog SPST switches that operate from a single +1.6 to +3.6 V supply.
CMOS process technology allows switching of analog signals that are within the supply voltage range (GND to $\mathrm{V}+$ ).
Figure 11. 16-pin TQFN Block Diagrams


Table 6. Truth Tables

| Device | Input | Switch State |  |
| :---: | :---: | :---: | :---: |
| AS1751 | Low | Off |  |
|  | High | On |  |
| AS1752 | Low | On |  |
|  | High | Off |  |
| AS1753 | Low | Switches 1, 3 = Off |  |
|  | High | Switches 1, 3 = On |  |
|  |  | Switches 2, 4 = On |  |
|  |  |  |  |

## ON-Resistance

When powered from a +3 V supply, the low ( $0.9 \Omega$, max) ON-resistance allows high-speed, continuous signals to be switched in a variety of applications.

## Bi-Directional Switching

Pins NOx, NCx, and COMx are bi-directional, thus they can be used as inputs to- or outputs from other components.

## Analog Signal Levels

Analog signals ranging over the entire supply voltage range (V+ to GND) can be switched with very little change in ONresistance (see Typical Operating Characteristics on page 6).

## Logic Inputs

The devices' logic inputs can be driven up to +3.6 V regardless of the supply voltage value. For example, with a +1.8 V supply, IN $x$ may be driven low to GND and high to +3.6 V . This allows the devices to interface with +3 V systems using a supply of less than 3 V .

## 9 Application Information

## Power Supply Sequencing

Proper power-supply sequencing is critical for proper switch operation. The power supplies should be started up in the following sequence:

1. $\mathrm{V}+$
2. $\mathrm{NO} x, \mathrm{NC} x, \mathrm{COM} x$

Note: Do not exceed the absolute maximum ratings (see page 2 ).

## Overvoltage Protection

ON-resistance increases slightly at lower supply voltages.
Figure 12. Overvoltage Protection using 2 External Blocking Diodes


Adding diode D2 to the circuit shown in Figure 12 causes the logic threshold to be shifted relative to GND. Diodes D1 and D2 also protect against overvoltage conditions.
For example, in the circuit shown in Figure 12, if the supply voltage goes below the absolute maximum rating, and if a fault voltage up to the absolute maximum rating is applied to an analog signal pin, no damage will result.

## Power Supply Bypass

Power supply connections to the devices must maintain a low impedance to ground. This can be done using a bypass capacitor, which will also improve noise margin and prevent switching noise propagation from the $V+$ supply to other components.
A $0.1 \mu \mathrm{~F}$ bypass capacitor, connected from $\mathrm{V}+$ to GND (see Figure 18 on page 11), is adequate for most applications.

## Logic Inputs

Driving INx Rail-to-Rail will help minimize power consumption.

## Layout Considerations

High-speed switches require proper layout and design procedures for optimum performance.

- Short, wide traces should be used to reduce stray inductance and capacitance.
- Bypass capacitors should be as close to the device as possible.
- Large ground planes should be used wherever possible.


## Timing Diagrams and Test Setups

Figure 13. AS1751/AS1753 Test Circuit and Timing Diagram


Figure 14. AS1752IAS1753 Test Circuit and Timing Diagram


Figure 15. AS1753 Test Circuit and Timing Diagram


Figure 16. Charge Injection


Figure 17. NOx, NCx, and COMx Capacitance


Figure 18. Off-Isolation, On-Loss, and Crosstalk


## Notes:

1. Measurements are standardized against short-circuit at socket terminals.
2. Off-isolation is measured between COMx and the off $\mathrm{NCx} / \mathrm{NO} x$ terminal on each switch. Off-isolation = 20log (Vout/ VIN).
3. On-loss is measured between COMx and the on NCx/NOx terminal on each switch. On-loss $=20 \log$ (Vout/Vin).
4. Signal direction through the switch is reversed; worst values are recorded.

## Package Drawings and Markings

The devices are available in an 16-pin TQFN package and an 14-pin TSSOP package.
Figure 19. 16-pin TQFN Package



EVEN TERMINAL SIDE

| Common Dimensions |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: |
| Symbol | Min | Nom | Max | Notes |
| aaa |  | 0.15 |  | 1,2 |
| bbb |  | 0.10 |  | 1,2 |
| ccc |  | 0.10 |  | 1,2 |
| ddd |  | 0.05 |  | 1,2 |
| A | 0.70 | 0.75 | 0.80 |  |
| A1 | 0.00 | 0.02 | 0.05 |  |
| A3 |  | 0.20 |  |  |
| L1 | 0.03 |  | 0.15 |  |
| D BSC |  | 3.00 |  | $1,2,10$ |
| E BSC |  | 3.00 |  | $1,2,10$ |
| D2 | 1.30 | 1.45 | 1.55 | $1,2,10$ |
| E2 | 1.30 | 1.45 | 1.55 | $1,2,10$ |
| L | 0.30 | 0.40 | 0.50 | $1,2,10$ |
| N |  | 16 |  | $1,2,10$ |
| ND |  | 4 |  | $1,2,10$ |
| NE |  | 4 |  | $1,2,10$ |

## Notes:

1. Dimensioning and tolerancing conform to ASME Y14.5M-1994.
2. All dimensions are in millimeters; angles in degrees.
3. N is the total number of terminals.
4. The terminal \#1 identifier and terminal numbering convention shall conform to JEDEC 95 SPP-012. Details of terminal \#1 identifier are optional but must be located within the zone indicated. The terminal \#1 identifier may be either a mold or marked feature.
5. Dimension $b$ applies to metallized terminal and is measured between 0.15 and 0.30 mm from terminal tip. If one end of the terminal has the optional radius, the $b$ dimension should not be measured in that radius area.
6. Dimensions ND and NE refer to the number of terminals on each $D$ and $E$ side, respectively.
7. Depopulation is possible in a symmetrical fashion.
8. Figure 19 is shown for illustration only and does not represent any specific variation.
9. All variations may be constructed per Figure 19, however variations may alternately be constructed between square or rectangle shape per dimensions $D$ and $E$.
10. Refer to the Dimensions Table for a complete set of dimensions.
11. Bilateral coplanarity zone applies to the exposed heat sink slug as well as the terminals.
12. Depending on the method of lead termination at the edge of the package, pullback (L1) may be present. L minus L1 to be $\geq 0.33 \mathrm{~mm}$.
13. For variations with more than one lead count for a given body size and terminal pitch, each lead count for that variation is denoted by a dash number (e.g., -1 or -2 ).
14. NJR designates non-JEDEC registered package.

Figure 20. 14-pin TSSOP Package


| Symbol | 0.65 mm Lead Pitch ${ }^{1,2}$ |  |  | Note | Symbol | 0.65mm Lead Pitch ${ }^{1,2}$ |  |  | Note |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  | Min | Nom | Max |  |  | Min | Nom | Max |  |
| A | - | - | 1.10 |  | $\theta 1$ | $0^{\circ}$ | - | $8^{\circ}$ |  |
| A1 | 0.05 | - | 0.15 |  | L1 | 1.0 Ref |  |  |  |
| A2 | 0.85 | 0.90 | 0.95 |  | aaa | 0.10 |  |  |  |
| L | 0.50 | 0.60 | 0.75 |  | bbb | 0.10 |  |  |  |
| R | 0.09 | - | - |  | ccc | 0.05 |  |  |  |
| R1 | 0.09 | - | - |  | ddd | 0.20 |  |  |  |
| b | 0.19 | - | 0.30 | 5 | e | 0.65 BSC |  |  |  |
| b1 | 0.19 | 0.22 | 0.25 |  | $\theta 2$ | $12^{\circ} \mathrm{Ref}$ |  |  |  |
| c | 0.09 | - | 0.20 |  | $\theta 3$ | $12^{\circ} \mathrm{Ref}$ |  |  |  |
| c1 | 0.09 | - | 0.16 |  |  |  |  |  |  |
| Variations |  |  |  |  |  |  |  |  |  |
| D | 4.90 | 5.00 | 5.10 | 3, 8 | e | 0.65 BSC |  |  |  |
| E1 | 4.30 | 4.40 | 4.50 | 4,8 | N | 14 |  |  | 6 |
| E | 6.4 BSC |  |  |  |  |  |  |  |  |

## Notes:

1. All dimensions are in millimeters; angles in degrees.
2. Dimensions and tolerancing per ASME Y14.5M-1994.
3. Dimension D does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Dimension E1 does not include interlead flash or protrusion. Interlead flash or protrusion shall not exceed 0.25 mm per side.
5. Dimension $b$ does not include dambar protrusion. Allowable dambar protrusion shall be 0.08 mm total in excess of dimension b at maximum material condition. Dambar cannot be located on the lower radius of the foot. Minimum space between protrusion and adjacent lead is 0.07 mm for 0.5 mm pitch packages.
6. Terminal numbers shown are for reference only.
7. Datums $A$ and $B$ to be determined at datum plane $H$.
8. Dimensions D and E1 to be determined at datum plane H .
9. This dimension applies only to variations with an even number of leads per side. For variations with an odd number of leads per package, the center lead must be coincident with the package centerline, datum $A$.
10. Cross section A-A to be determined at 0.10 to 0.25 mm from the leadtip.

## 10 Ordering Information

The devices are available as the standard products shown in Table 7.
Table 7. Ordering Information

| Model | Description | Delivery Form | Package |
| :---: | :---: | :---: | :---: |
| AS1751S | SPST Switch | Tube | 14-TSSOP |
| AS1751S-T | Quad SPST Switch | Tape and Reel | 14-TSSOP |
| AS1751V ${ }^{\dagger}$ | Quad SPST Switch | Tray | 16-TQFN 3mmx3mm |
| AS1751V- ${ }^{\dagger}$ | Quad SPST Switch | Tape and Reel | 16-TQFN 3mmx3mm |
| AS1752S | Quad SPST Switch | Tube | 14-TSSOP |
| AS1752S-T | Quad SPST Switch | Tape and Reel | 14-TSSOP |
| AS1752V ${ }^{\dagger}$ | Quad SPST Switch | Tray | 16-TQFN 3mmx3mm |
| AS1752V- ${ }^{\dagger}$ | Quad SPST Switch | Tape and Reel | 16-TQFN 3mmx3mm |
| AS1753S | Quad SPST Switch | Tube | 14-TSSOP |
| AS1753S-T | Quad SPST Switch | Tape and Reel | 14-TSSOP |
| AS1753V ${ }^{\dagger}$ | Quad SPST Switch | Tray | 16-TQFN 3mmx3mm |
| AS1753V-T ${ }^{\dagger}$ | Quad SPST Switch | Tape and Reel | 16-TQFN 3mmx3mm |

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[^0]:    ${ }^{\dagger}$ Future Product

